

GENERAL DESCRIPTION

The DAC1331X core is a CMOS 10-bit dual D/A Converter Wireless Lan application. The typical conversion rate is 40MHz. It is fabricated with 0.18 μ m process and operated at 1.8V single power.

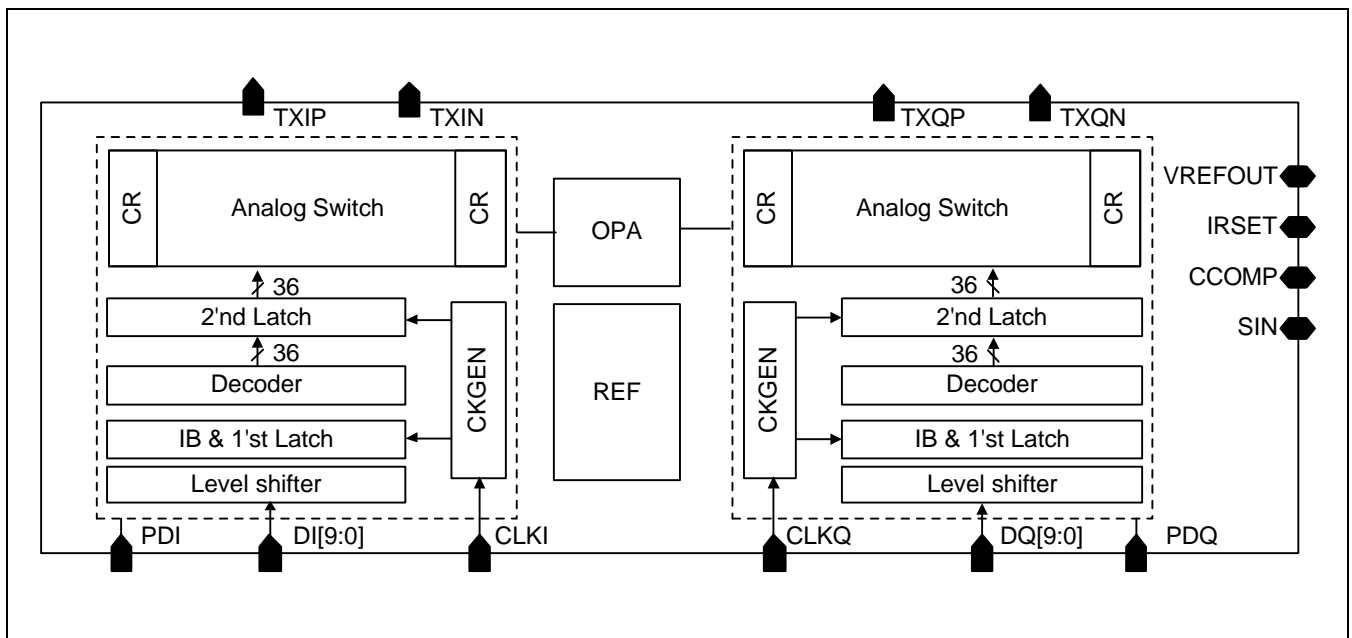
FEATURES

- 40MSPS operation
- +1.8V single power supply
- 0 ~ 0.5V output swing
- Power down mode (active HIGH)
- Two's complementary parallel input

TYPICAL APPLICATION

- Wireless Lan Card
- CDMA

FUNCTIONAL BLOCK DIAGRAM



1.3 (Apr. 2002)

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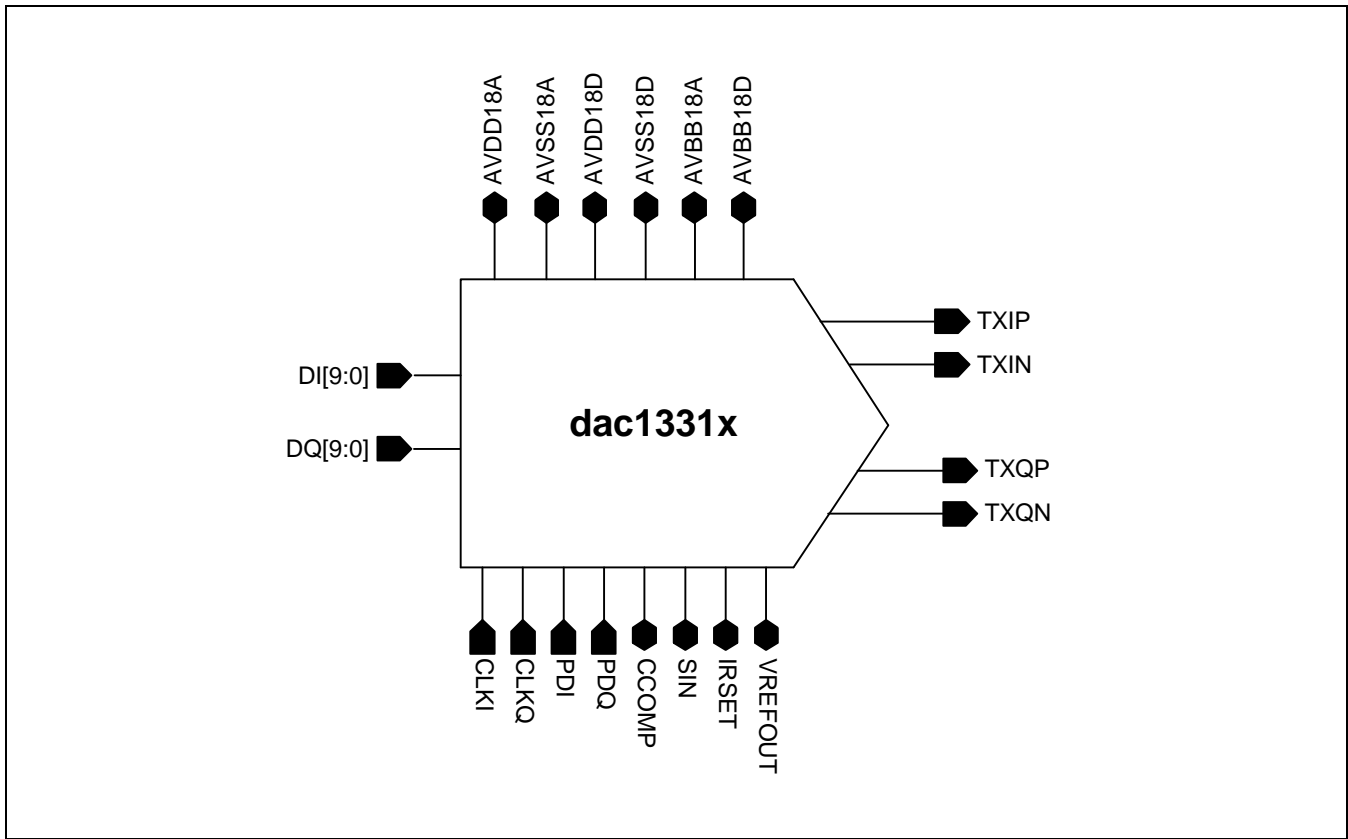
CORE PIN DESCRIPTION

Pin Name	I/O Type	I/O Pad	Pin Description
TXIP, TXIN TXQP, TXQN	AO	poa_abb	Analog Output Voltage
DI[9:0], DQ[9:0]	DI	picc_abb	Digital Input
PDI, PDQ	DI	picc_abb	power down and standby mode
CLKI, CLKQ	DI	picc_abb	Clock Input
VREFOUT	AI	poa_abb	Bias (0.4V)
IRSET	AO	poa_abb	Probing pin
CCOMP	AB	poa_abb	Using Compensation Capacitor(0.1uF)
SIN	AB	poa_abb	Using Compensation Capacitor(0.1uF)
AVDD18A	AP	vdd1t	Analog Power
AVSS18A	AG	vss1t	Analog Ground
AVDD18D	DP	vdd1t	Digital Power
AVSS18D	DP	vss1t	Digital Ground
AVBB18A	AG	vbb1t	Analog Ground (bulk bias)
AVBB18D	AG	vbb1t	Analog Ground (bulk bias)

I/O Type Abbr.

- AI: Analog Input
- DI: Digital Input
- AO: Analog Output
- DO: Digital Output
- AB: Analog Bi-direction
- DB: Digital Bi-direction
- AP: Analog Power
- AG: Analog Ground
- DP: Digital Power
- DG: Digital Ground

CORE CONFIGURATION



FUNCTIONAL DESCRIPTION

This is 10bit 40MSPS dual digital to analog data converter and uses segment architecture for 5bits of MSB sides, binary-weighted architecture for 5bits of LSB side. It contains of First latch block, decoder block, Second latch block, AMP block, switch buffer block, REF block for power down, CM(current mirror) block and analog switch block. This core uses reference current to decide the 1LSB current size by dividing the reference current by 32 times. So the reference current must be constant and the switch's physical real size can be constant by using OPA block with high DC gain. The most significant block of this core is analog switch block and it must maintain the uniformity at each switch, so layout designer must care of the matching characteristics on analog switch and CM block. To adjust full current output, you must force the "vrefout" voltage source value.

- Error** : Linearity error is defined as the maximum deviation of the actual analog output from the ideal output, determined by a straight line drawn from zero to full scale.
- Monotonicity** : A D/A converter is monotonic if the output either increases or remains constants as the digital input increases.
- Offset Error** : The deviation of the output current from the ideal of zero is called offset error. For IO, 0mV output expected when the inputs are all 0s.
- Gain Errors** : The difference between the actual and ideal output span. The actual span is determined by the output when all inputs are set to 1s minus the output when all inputs are set to 0s.
- Output Compliance Range** : The range of allowable voltage at the output of a current-output DAC. Operation beyond the maximum compliance limits may cause either output stage saturation or breakdown resulting in nonlinear performance.
- Settling Time** : The time required for the output to reach and remain within a specified error band about its final value, measured from the start of the output transition.
- Glitch Impulse** : Asymmetrical switching times in a DAC give rise to undesired output transients that are quantified by a glitch impulse. It is specified as the net area of the glitch in pV-s.

ABSOLUTE MAXIMUM RATINGS

Characteristic	Symbol	Values	Unit
Supply Voltage	VDD	2.5	V
Digital Input Voltage	CK PD VIN	AVSS18D to AVDD18D	V
Storage Temperature Range	Tstg	-45 to 150	°C

NOTES:

1. It is strongly recommended that to avoid power latch-up all the supply Pins(AVDD18A,AVSS18A) be driven from the same source.
2. Absolute Maximum Rating values applied individually while all other parameters are within specified operating conditions. Function operation under any of these conditions is not implied.
3. Applied voltage must be current limited to specified range.
4. Absolute Maximum Ratings are value beyond which the device may be damaged permanently. Normal operation is not guaranteed.

RECOMMENDED OPERATING CONDITIONS

Characteristics	Symbol(Name)	Min	Typ	Max	Unit
Operating Supply Voltage	AVDD25D-AVSS25D AVDD25A-AVSS25A	1.7	1.8	1.9	V
Reference Input Voltage(External)	VREFOUT	–	0.4	–	V
Operating Temperature Range	TOPR	-40	–	85	°C

NOTE: It is strongly recommended that to avoid power latch-up all the supply pins(AVDD18A,AVDD18D) be driven from the same source.

DC ELECTRICAL CHARACTERISTICS

Characteristics	Symbol	Min	Typ	Max	Unit
Resolution	-	-	10	-	Bits
Differential Linearity Error	DLE	-	-	±1	LSB
Integral Linearity Error	ILE	-	-	±2	LSB
Monotonicity	-	-	Guaranteed	-	-
Analog Output Voltage Range	-	-	1 V _{PP} 0.5 V _{PP}	-	Differential Single ended
Maximum Output Compliance	Voc	0	-	+ 0.6	V
External Reference Voltage	-	-	0.4	-	V
Full Scale Error (differential)		-50	-	50	mV
IQ Gain Mismatch		-0.18		0.18	dB
Power Supply Current	I _s	-	25	-	mA

NOTE: Converter Specifications (unless otherwise specified)

Output Loading Condition : Output Load Capacitor = 10pF ,Output Load Resistor = 50Ω

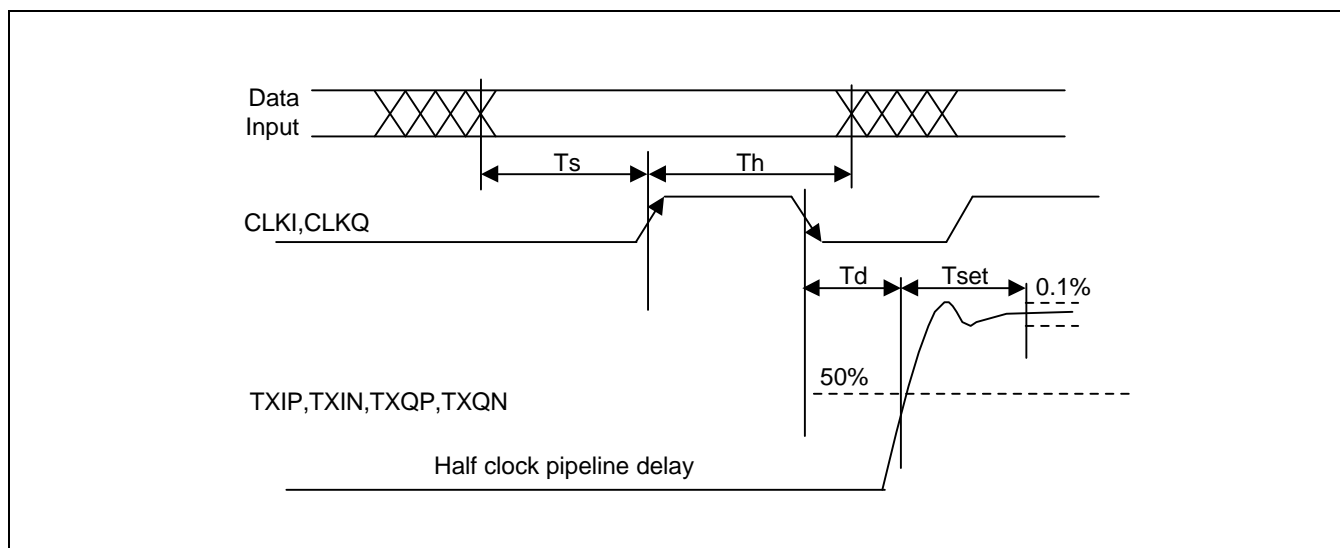
AC ELECTRICAL CHARACTERISTICS

Characteristics	Symbol	Min	Typ	Max	Unit	Conditions
Maximum Conversion Rate	f _c	-	40		MSPS	Data Rate = 1 ~ 17MHz
Dynamic Supply Current	I _{vdd1}	-	25	-	mA	I _{vdd1} = I _{AVDD18A} + I _{AVDD18D}
Dynamic Supply Current (Power Down Mode)	I _{vdd2}	-	50	-	uA	I _{vdd2} = I _{AVDD18A} + I _{VRT} + I _{AVDD18D} PDI,PDQ=HIGH
Analog Output Delay	T _d	-	20	-	ns	DATA : All Low to All High
Analog Output Rise Time	T _r	-	30	-	ns	DATA : All Low to All High
Analog Output Fall Time	T _f	-	3.0	-	ns	DATA : All Low to All High
Analog Output Settling Time	T _s	-	50	-	ns	DATA : All Low to All High
Glitch Impulse	GI	-	100	-	pVsec	
Feedthrough	fdth	-	90	-	dB	
Setup Time	T _s	-	1	-	nsec	
Hold Time	T _h	-	1	-	nsec	
Power Down On/Off time	-	-	500/500	-	usec	PDI/PDQ : LOW to HIGH HIGH to LOW
SNDR(F _{out} =1MHz, F _{ck} =40MHz)	SNDR	48	-	-	dB	F _{out} = 1 ~ 17MHz

NOTES:

1. The above parameters are guaranteed over the full temperature range.
2. Clock and data feed through is a function of the amount of overshoot and undershoot on the digital inputs Settling time does not include clock and data feed through . Glitch impulse include clock and data feed through.
3. Setup and Hold Time are simulation values, not a test result.

TIMING DIAGRAM (FOR ONE CHANNEL)



NOTES:

1. Output delay measured from the 50% point of the rising edge of CLKI,CLKQ to the full scale transition.
2. Settling time measured from the 50% point of full scale transition to the output remaining within $\pm 1,2$ LSB..
3. Output rise/fall time measured between the 10% and 90% points of full scale transition.

PC BOARD LAYOUT CONSIDERATIONS

1. PC Board Considerations

To minimize Noise On The Power Lines And The Ground Lines, The Digital Inputs Need To Be Shielded And Decoupled. This Trace Length Between Groups Of AVDD18A,AVDD18D pins short as possible so as to minimize inductive ringing.

2. Supply Decoupling and Planes

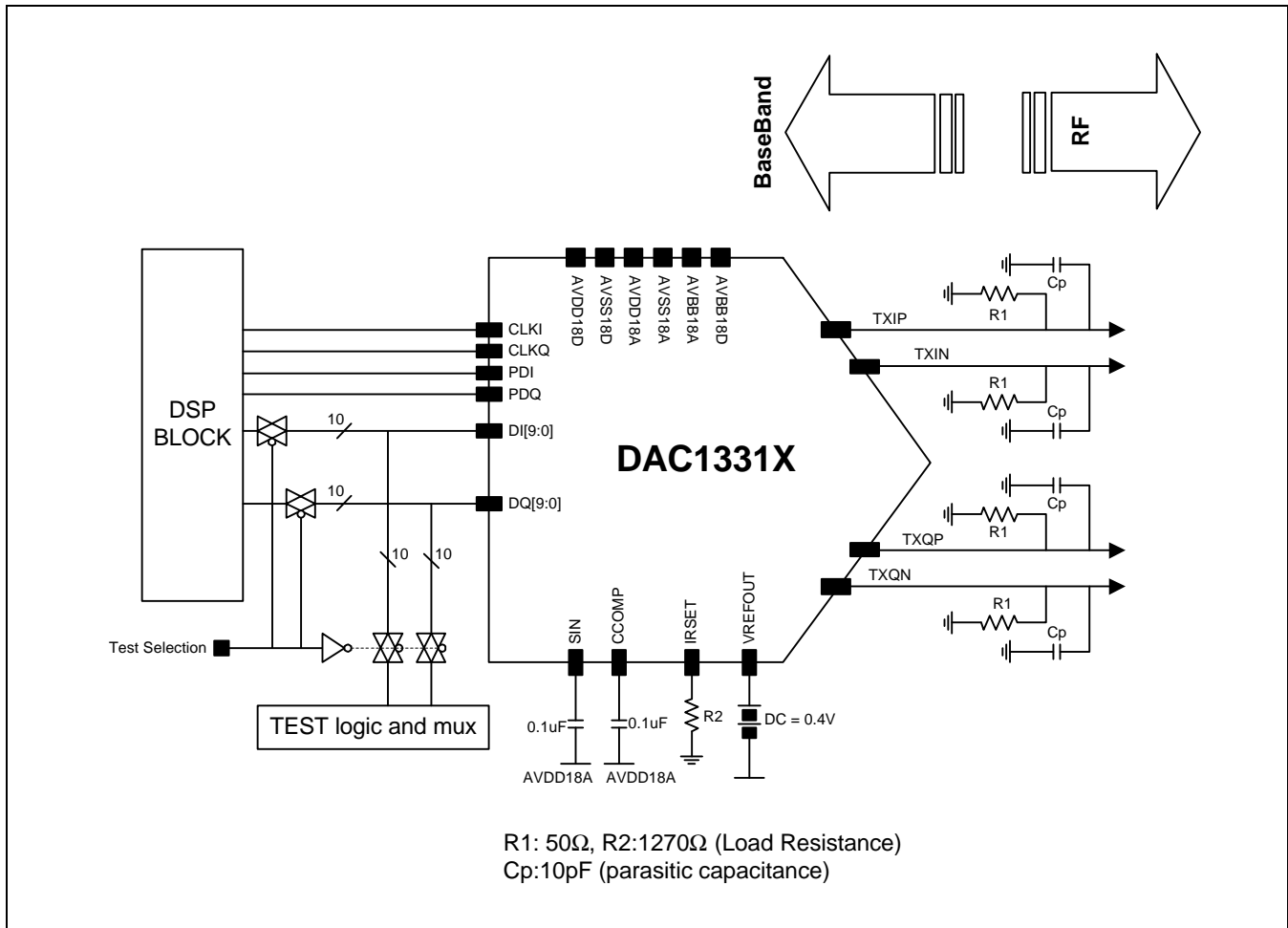
For the de-coupling capacitor between the power line and the ground line, 0.1mF ceramic capacitor is used in parallel with a 10mF tantalum capacitor. The digital power plane (AVDD18D) and analog power plane (AVDD18A) are connected through a ferrite bead, and also the digital ground plane (AVSS18D) and the analog ground plane (AVSS25A). This ferrite bead should be located within 3inches of the DAC1331X. The analog power plane supplies power to the DAC1331X of the analog output pin and related devices.

3. Analog Signal Interconnection

To minimized noise pickup and reflections due to impedance mismatch, the DAC1331X should be located as close as possible to the output connector.

The line between DAC output and monitor input should also be regarded as a transmission line. Due to the fact, it can cause problems in transmission line mismatch. As a solution to these problems, the double-termination methods used. By using this, both ends of the termination lines are matched, providing an ideal, non-reflective system.

CORE EVALUATION GUIDE

**NOTES:**

In order to reduce the number of I/O pad, you can tie AVBB18A, AVBB18D port to AVSS18A and share the AVDD18D, AVSS18D with other digital power and ground. We don't offer Test logic block. So if you need test logic block, you must make it by yourself as.

The voltage is scaled factor of 1/32 for this core. The full scale current is given as the decimal value equivalent to the digital code.

1. Resolution

If you want to change the 10bit resolution to 8bit resolution with the same output voltage, connect the rest lower two pin to ground.

2. Output Range Alteration

In order to change the output swing, use following equation.

$$V_{out}(TXIP, TXIN, TXQP, TXQN) = \{ V_{refout} / (R2 * M) \} * (1023) * 50\Omega$$

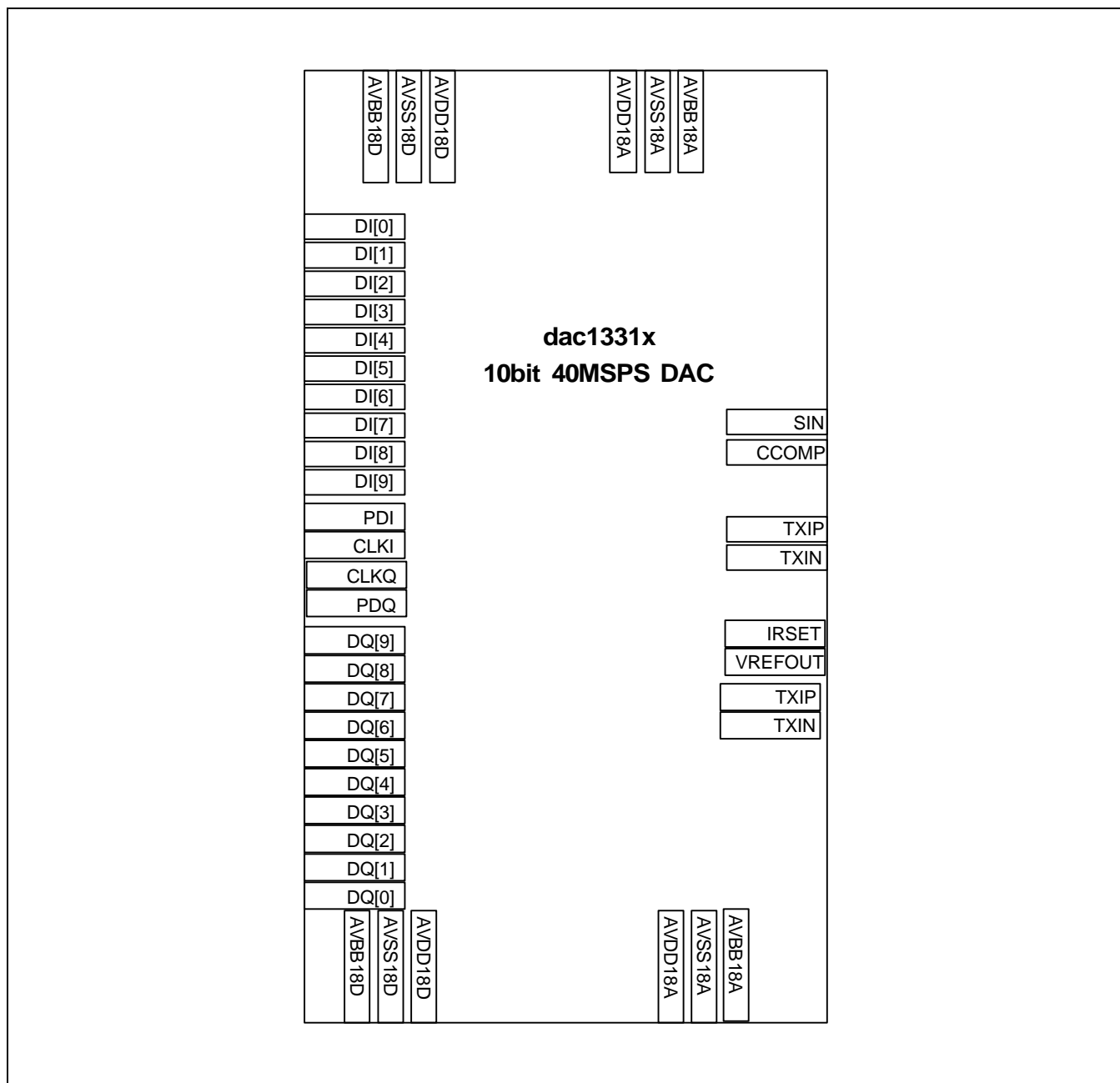
The maximum output swing level is 0.5V when M, R2 are 32, 2.23kΩ respectively.

PHANTOM CELL INFORMATION

- Pins of the core can be assigned externally (Package pins) or internally (internal ports) depending on design methods.

The term "External" implies that the pins should be assigned externally like power pins.

The term "External/internal" implies that the applications of these pins depend on the user.



Pin Name	Pin Usage	Pin Layout Guide
AVDD18A	External	<ul style="list-style-type: none"> - Maintain the large width of lines as far as the pads. - place the port positions to minimize the length of power lines. - Do not merge the analog powers with another power from other blocks. - Use good power and ground source on board.
AVSS18A	External	
AVBB18A	External	
AVDD18D	External	
AVSS18D	External	
AVBB18D	External	
CCOMP	External	<ul style="list-style-type: none"> - Do not overlap with digital lines. - Maintain the shortest path to pads. - Separate from all other analog signals - Maintain the larger width and the shorter length as far as the pads. - Separate from all other digital lines.
IRSET	External	
SIN	External	
TXIP/TXIN	External	
TXQP/TXQN	External	
CLKI	External/Internal	<ul style="list-style-type: none"> - Separated from the analog clean signals if possible. - Do not exceed the length by 1,000um. - In Phantom cell in case of many ports of one power name , you must drag the ports individually to PAD in parallel. - Customer must use two PAD's individually for analog power ports because of PAD's current limitation.
CLKQ	External/Internal	
DI[9]	External/Internal	
DI[8]	External/Internal	
DI[7]	External/Internal	
DI[6]	External/Internal	
DI[5]	External/Internal	
DI[4]	External/Internal	
DI[3]	External/Internal	
DI[2]	External/Internal	
DI[1]	External/Internal	
DI[0]	External/Internal	
PDI	External/Internal	
PDQ	External/Internal	
DI[9]	External/Internal	
DI[8]	External/Internal	
D[7]	External/Internal	
D[6]	External/Internal	
D[5]	External/Internal	
D[4]	External/Internal	
D[3],D[2]	External/Internal	
D[1],D[0]	External/Internal	

FEEDBACK REQUEST

We appreciate your interest in our products. If you have further questions, please specify in the attached form. Thank you very much.

DC / AC Electrical Characteristic					
Characteristics	Min	Typ	Max	Unit	Remarks
Supply Voltage				V	
Power dissipation				mW	
Resolution				Bits	
Analog Output Voltage				V	
Operating Temperature				°C	
Output Load Capacitor				pF	
Output Load Resistor				Ω	
Integral Non-Linearity Error				LSB	
Differential Non-Linearity Error				LSB	
Maximum Conversion Rate				MHz	

Voltage Output DAC					
Characteristics	Min	Typ	Max	Unit	Remarks
Reference Voltage TOP BOTTOM				V	
Analog Output Voltage Range				V	
Digital Input Format	Binary Code or 2's Complement Code				

Current Output DAC					
Characteristics	Min	Typ	Max	Unit	Remarks
Analog Output Maximum Current				mA	
Analog Output Maximum Signal Frequency				kHz	
Reference Voltage				V	
External Resistor for Current Setting (RSET)				Ω	
Pipeline Delay				sec	

- Do you want to Power down mode?
- Do you want to Internal Reference Voltage (BGR)?
- Which do you want to serial input type or parallel input type?

HISTORY CARD

Version	Date	Modified Items	Comments
Ver 1.0	01.05.27	Original version published	
Ver 1.1	01.08.03	VREFOUT : 0.7V → 0.4V Power Down On/Off Time addition (5/10 page) Power Down Current (5/10 page)	
Ver 1.2	02.02.28	Typo correction	
Ver 1.3	02.04.20	Add Phantom cell guide	